

## DESCRIPTION

The MX2362 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

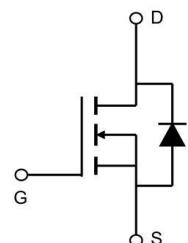
## GENERAL FEATURES

- $V_{DS}=60V$ ,  $I_D=2.8A$
- $R_{DS(ON)}(\text{Typ.})=130\text{m}\Omega$  @  $V_{GS}=2.5V$
- $R_{DS(ON)}(\text{Typ.})=95\text{m}\Omega$  @  $V_{GS}=4.5V$
- $R_{DS(ON)}(\text{Typ.})=87\text{m}\Omega$  @  $V_{GS}=10V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

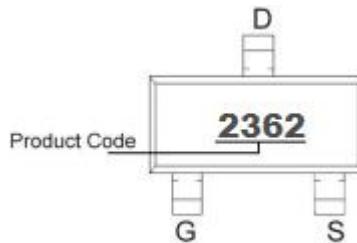
## APPLICATION

- Battery Switch
- DC/DC Converter

## PINOUT



Schematic diagram



Marking and pin Assignment



SOT-23 top view

## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MX2362	-55°C to 150°C	SOT-23	-

## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	2.8	A
Pulsed Drain Current <sup>(Note1)</sup>	$I_{DM}$	10	A
Maximum Power Dissipation	$P_D$	1.7	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

## THERMAL RESISTANCE

Thermal Resistance, Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	73.5	°C/W
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Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.


**ELECTRICAL CHARACTERISTICS**( $T_A=25^\circ C$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	1.0	1.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=2.5V, I_D=2A$	-	130	150	$m\Omega$
		$V_{GS}=4.5V, I_D=2.8A$	-	95	115	$m\Omega$
		$V_{GS}=10V, I_D=2.8A$	-	87	110	$m\Omega$

**Dynamic Characteristics**<sup>(Note 4)</sup>

Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, F=1.0MHz$	-	247	-	pF
Output Capacitance	$C_{oss}$		-	34	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	19.5	-	pF

**Switching Characteristics**<sup>(Note 4)</sup>

Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V, I_D=1.5A, V_{GS}=10V, R_{GEN}=1\Omega$	-	6	-	nS
Turn-on Rise Time	$t_r$		-	15	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	15	-	nS
Turn-Off Fall Time	$t_f$		-	10	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=30V, I_D=2.5A, V_{GS}=4.5V$	-	6	-	nC
Gate-Source Charge	$Q_{gs}$		-	1	-	nC
Gate-Drain Charge	$Q_{gd}$		-	1.3	-	nC

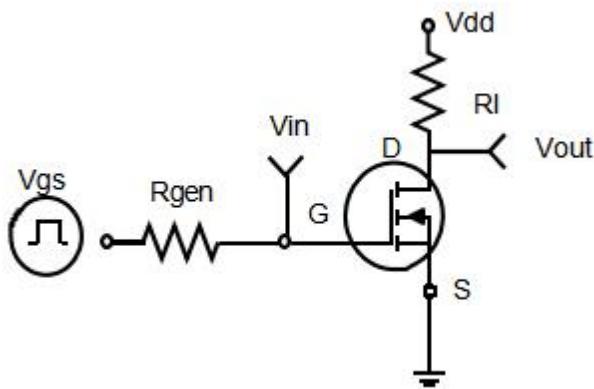
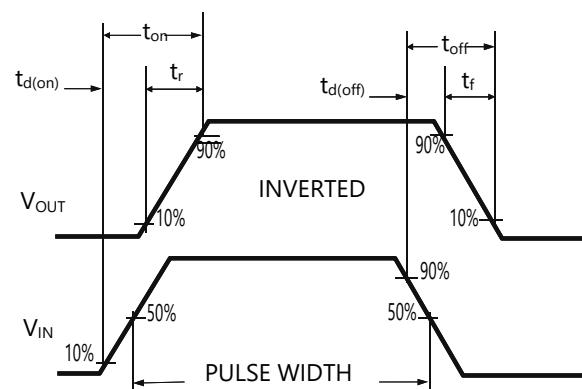
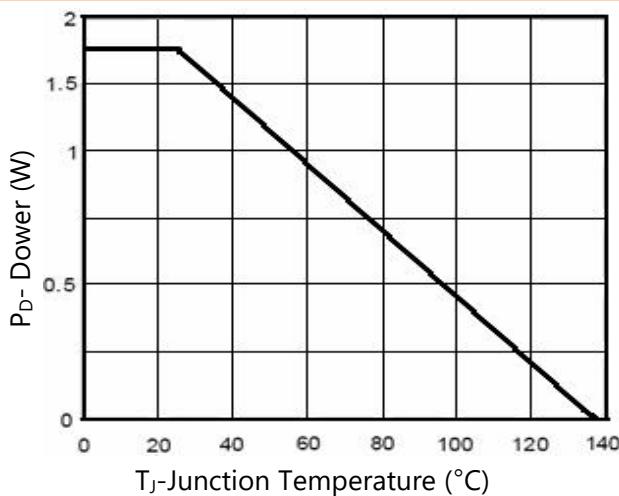
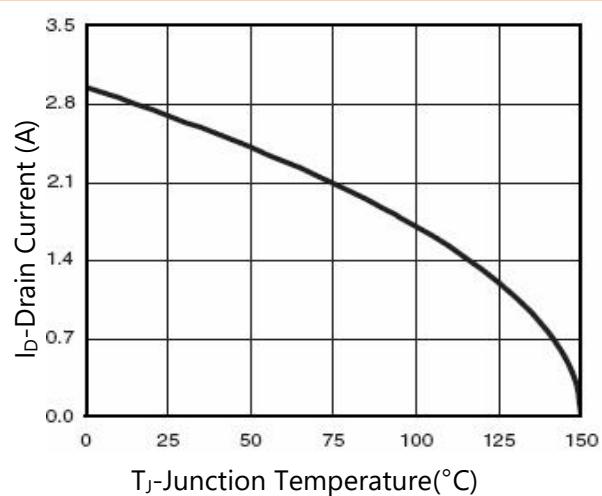
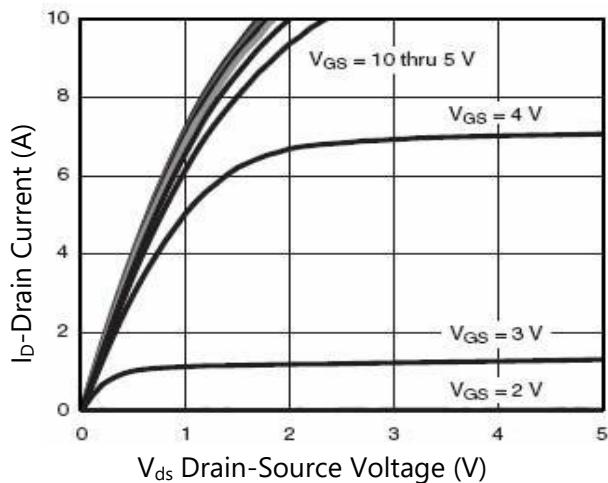
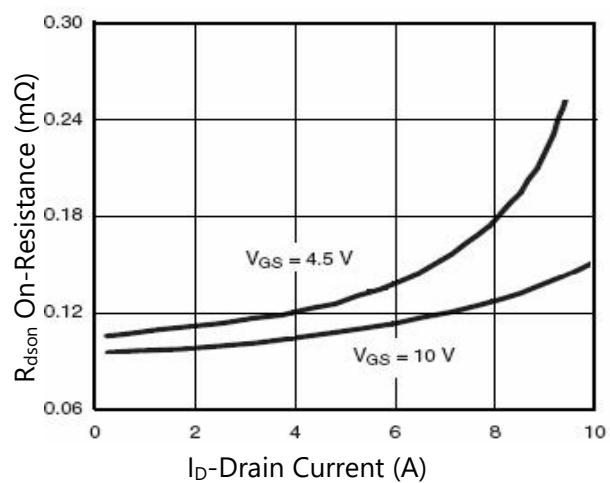
**Drain-Source Diode Characteristics**

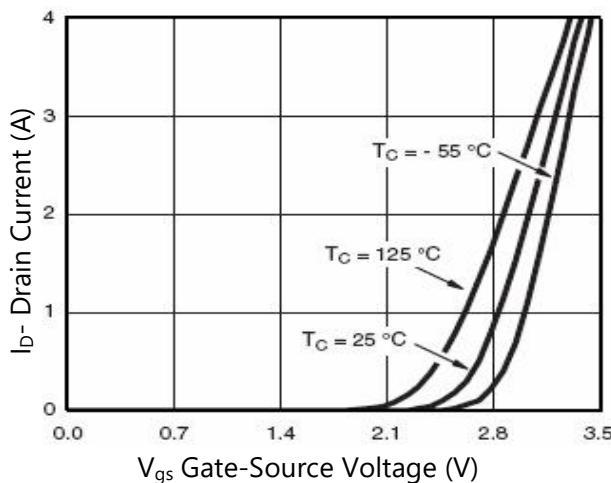
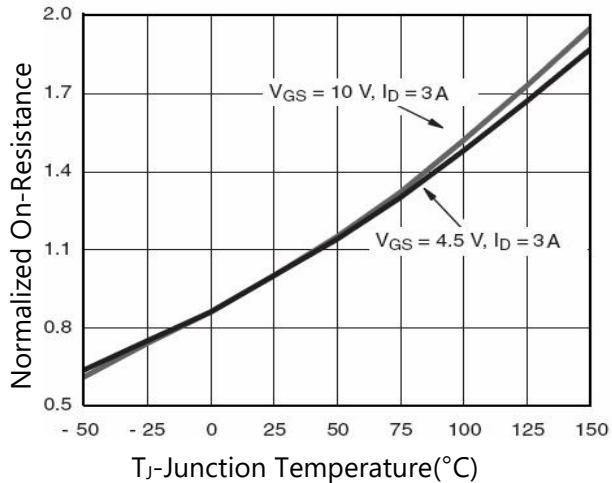
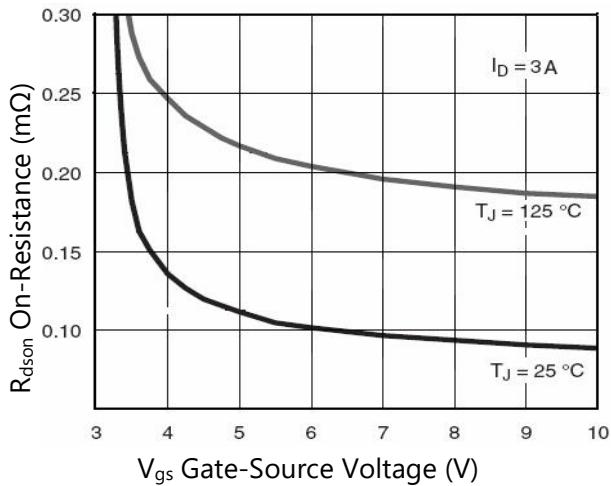
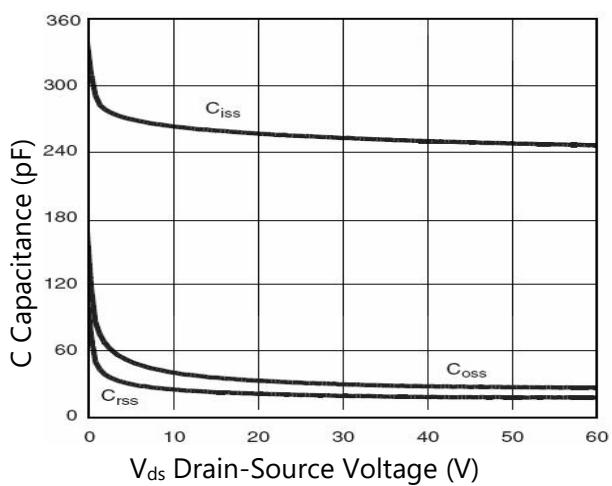
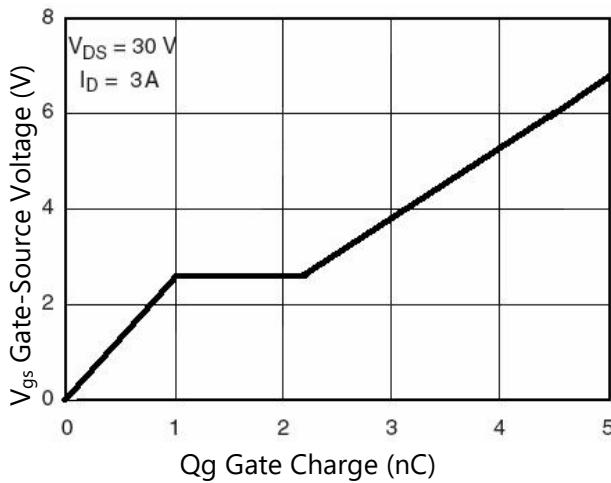
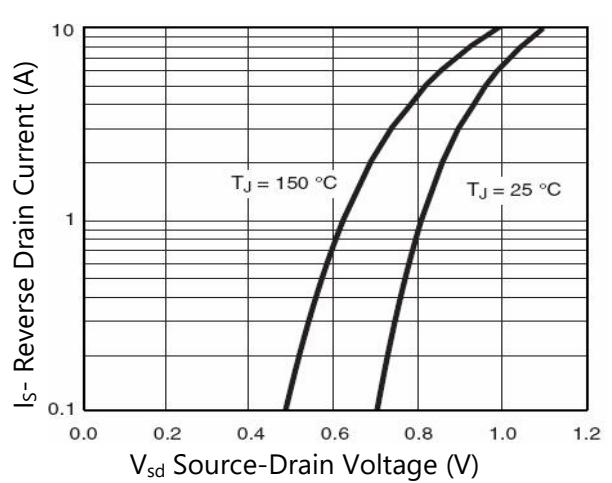
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{SD}$	$V_{GS}=0V, I_s=2.5A$	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_s$		-	-	3	A

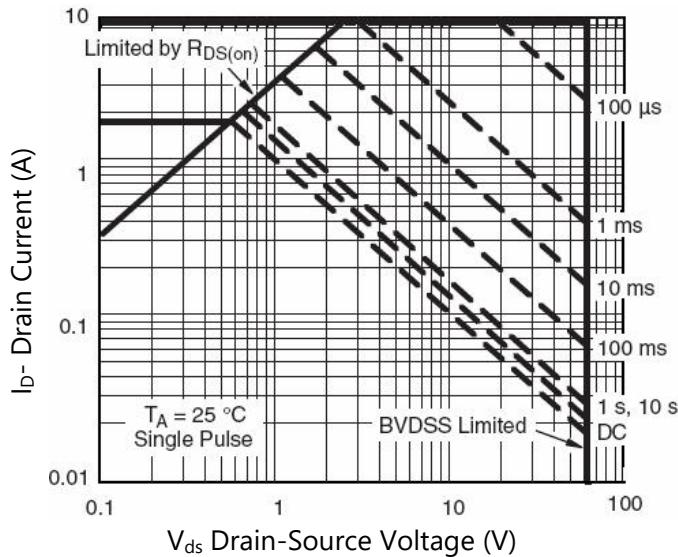
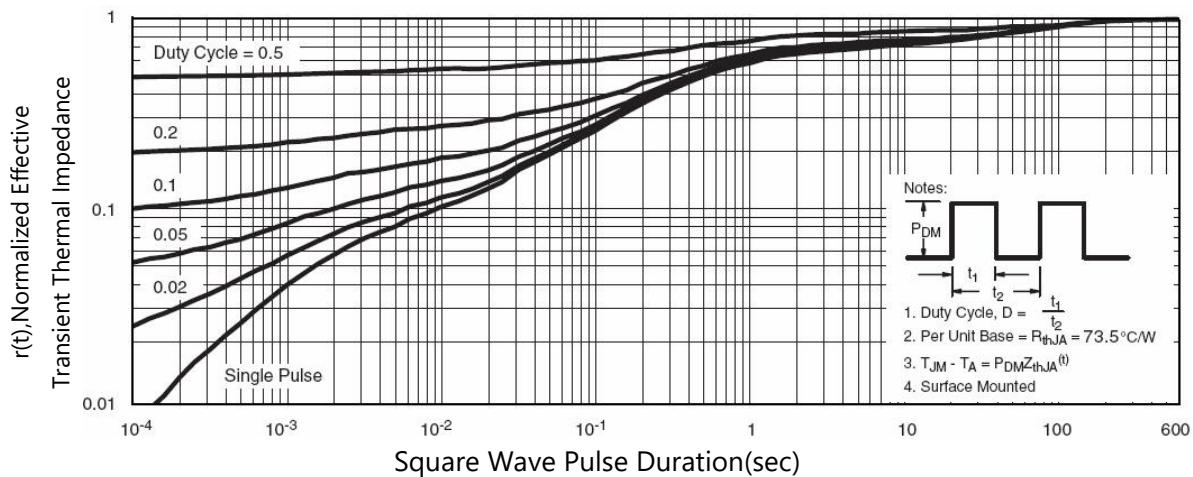
Note 2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.

Note 3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .

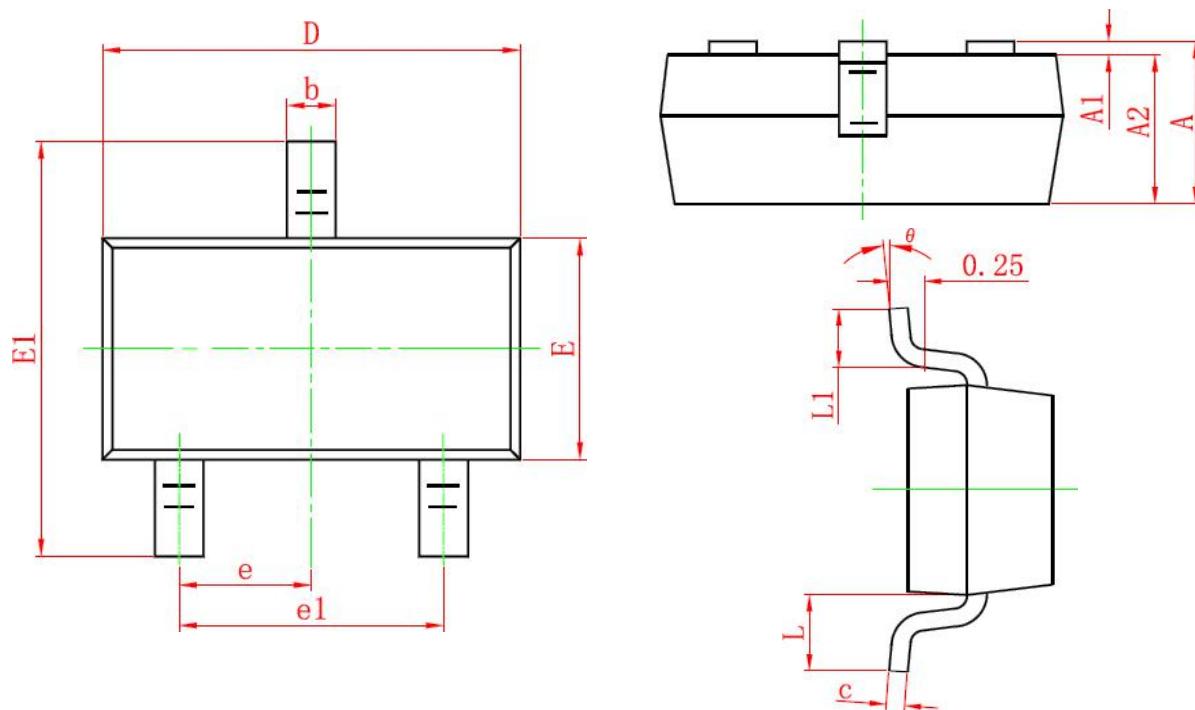
Note 4. Guaranteed by design, not subject to product.


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**
**Figure 1. Switching Test Circuit**

**Figure 2. Switching Waveform**

**Figure 3. Power Dissipation**

**Figure 4. Drain Current**

**Figure 5. Output Characteristics**

**Figure 6. R<sub>dson</sub> vs Drain Current**



**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**
**Figure 7. Transfer Characteristics**

**Figure 8.  $R_{dson}$  vs Junction Temperature**

**Figure 9.  $R_{dson}$  vs  $V_{gs}$** 

**Figure 10. Capacitance vs  $V_{DS}$** 

**Figure 11. Gate Charge**

**Figure 12. Source- Drain Diode Forward**



**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**
**Figure 13. Safe Operation Area**

**Figure 14. Normalized Maximum Transient Thermal Impedance**


## PACKAGE INFORMATION

**SOT-23**


Symbol	Dimensions in Millimeters	
	Min.	Max.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500